

# Thesis writing

To structurize work and all data I got before I have started to write thesis:

- Made contents and estimations of volume for each chapter and sections
- First I wanted to start from introduction part
  - \* read (selectively) TDR of ILC 2013 (overview, physics case)  
Quarks and Leptons, F. Halzen, A. D. Martin (sm, qcd, susy)  
Introduction to elementary particles. D. Griffiths  
russian internet sources (can I use references in literature for russian books?)
  - \* made some drafts for introduction part, but it steel need some time...
- Wrote some pieces about simulation part and continue with this now

# FCAL, LCC WS in Belgrad in October

Discussed with Sergey topics for talk:

- Comparison of segmentations by simulation
  - \* finish simulations and make their description in the thesis
  - \* Fatima works on setting and adjusting software for CMS group: ROOT, GEANT 4 and other additional libraries . We test together scripts, trying to run BeCaS.
- ADC. Nonlinear digitizing of BeamCal signals
  - Some numerical estimates on next slide.
- Sapphire prototype
  - Sergey making first rough model of sapphire calorimeter with rectangular shape, without holes for tubes

# Charge deposition in pads

Case:

1 TeV ILC

GaAs sensors, 0.3mm thickness

Charge collected in pad from

Max charge deposition from

MIP : 4.3fC

500GeV electron: 20 pC (~5000 MIPs)

background: 20 pC (for PS)

120 pC (for US)

-> Doesn't have sense to have inner part of calorimeter with US, because BG is not comparable, but much higher

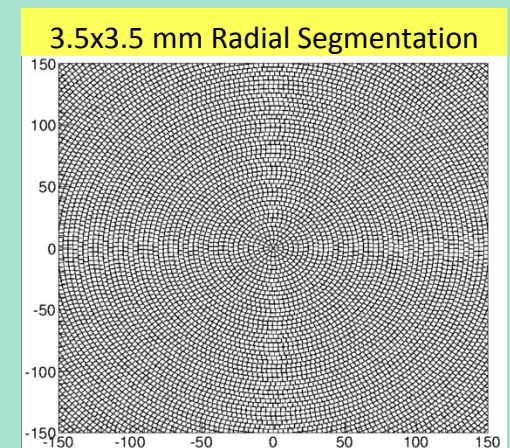
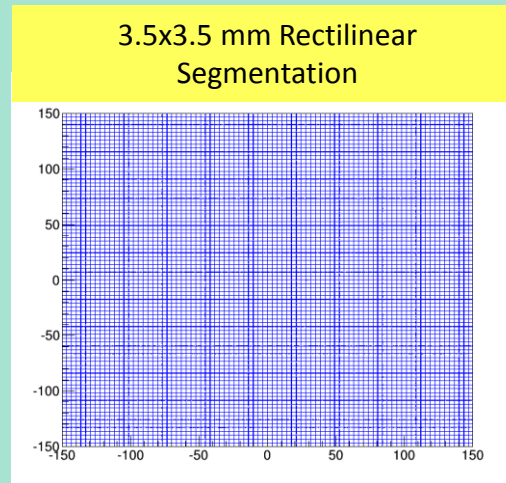
# Biweekly Clustering Meetings

Bruce and Christopher(new student?) are working now on update of BeamCal simulation study:

- SNR Comparison for Different Detector Models
- Comparison of Clustering Results Between Rectilinear and Radial Segmentation

I prepared instruction/manual for clustering algorithm codes, which include:

- Technical description of patterns and dimensions for US and PS
- Package of codes of clustering algorithm with example files
- Manual “how to use”



# other stuff

- There is an issue to make gold plating of GaAs wafers of 2011 design. We together with Hans have found that we currently have at hands 29 such sensors. (there are 2 more, but they are not at DESY at the moment)